

# APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate                             |  |  |
|------------------------|---|--|--|
| TO:                    | Please return this copy as a certification of your approval |  |  |
| Part No.:              | Checked & Approved by:                                      |  |  |
| Customer's Part No.:   | Date:   |  |  |

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| Part No. | : | SF1643    |
|----------|---|-----------|
| Pages    | : | 6         |
| Date     | : | 2017/3/28 |
| Revision | : | 1.0       |



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|--------------|-----|
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| Approved by: | 高亚京 |

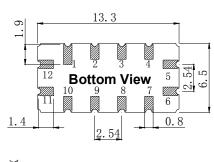
#### **Application**

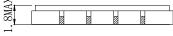
- High-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable Passband 12.00 MHz

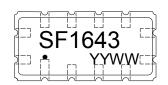
#### **Features**

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 13.30x6.50x1.80mm<sup>3</sup>
- Package Code QCC12
- Electrostatic Sensitive Device(ESD)

# Package Dimensions (Unit: mm)







# **Pin Configuration**

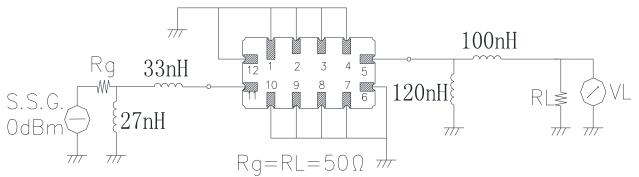
| Pin No.               | Description |  |  |
|-----------------------|-------------|--|--|
| 11                    | Input       |  |  |
| 5                     | Output      |  |  |
| 1,2,3,4,6,7,8,9,10,12 | Ground      |  |  |

# **Marking Description**

| S    | Trademark             |  |
|------|-----------------------|--|
| F    | SAW Filter            |  |
| 1643 | Part Number           |  |
| •    | Pin 1                 |  |
| YYWW | Year Code & Week Code |  |

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

# **Test Circuit(Bottom View)**



# **Performance**

# **Maximum Rating**

| Item                  |                  | Value      | Unit          |
|-----------------------|------------------|------------|---------------|
| DC Voltage            | $V_{DC}$         | 3          | V             |
| Operation Temperature | Т                | 25         | ${\mathbb C}$ |
| Storage Temperature   | T <sub>stg</sub> | -55 ~ +125 | $^{\circ}$    |
| RF Power Dissipation  | Р                | 10         | dBm           |

# **Electronic Characteristics**

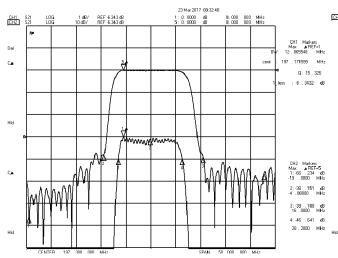
Test Temperature:  $25^{\circ}C \pm 2^{\circ}C$ 

Terminating source impedance:  $50\Omega$ Terminating load impedance:  $50\Omega$ 

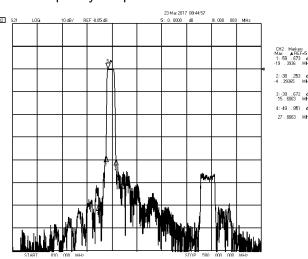
| Item                   |                   | Minimum | Typical | Maximum | Unit |
|------------------------|-------------------|---------|---------|---------|------|
| Center Frequency       | fc                |         | 197.30  |         | MHz  |
| Insertion Loss(min)    | IL                |         | 6.3     | 23.0    | dB   |
| Amplitude Ripple (p-p) | Δα                |         | 0.4     | 1.0     | dB   |
| 1 dB Bandwidth         | BW <sub>1dB</sub> | 12.0    | 12.8    |         | MHz  |
| Absolute Delay @Fc     | AD                |         | 0.86    |         | us   |
| Absolute Attenuation   | а                 |         |         |         |      |
| DC-137.80 MHz          |                   | 40      | 62      |         | dB   |
| 142.80-168.80 MHz      |                   | 40      | 52      |         | dB   |
| 172.80-187.80 MHz      |                   | 25      | 38      |         | dB   |
| 207.80-220.00 MHz      |                   | 35      | 39      |         | dB   |
| 220.00-500.00 MHz      |                   | 40      | 45      |         | dB   |

# **Frequency Characteristics**

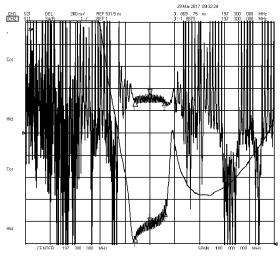
#### Frequency Response



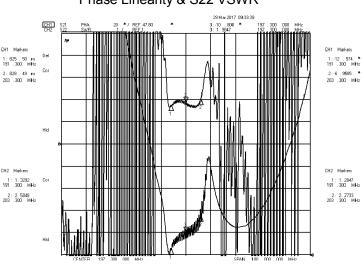
# Frequency Response (wideband)



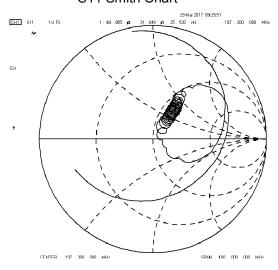
# Delay Ripple & S11 VSWR



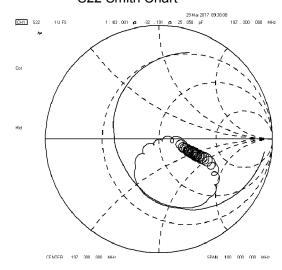
# Phase Linearity & S22 VSWR



#### S11 Smith Chart



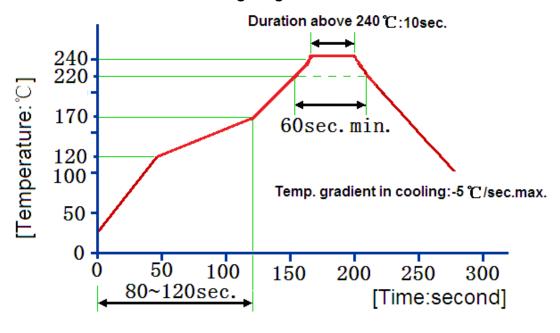
#### S22 Smith Chart



# Reliability (The SAW components shall remain electrical performance after tests)

| No. | Test item                       | Test condition  |  |  |
|-----|---------------------------------|---|--|--|
| 1   | Temperature                     | (1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h     |  |  |
|     | Storage                         | (2) Temperature: –55℃±3℃, Duration: 250h, Recovery time: 2h±0.5h        |  |  |
| 2   | Humidity Test                   | Conditions: 60℃±2℃, 90~95% RH Duration: 250h                            |  |  |
|     | T                               | Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch       |  |  |
| 3   | Thermal Shock                   | time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.             |  |  |
| 4   | A Mileartian Fatience           | Frequency of vibration: 10~55Hz Amplitude:1.5mm                         |  |  |
| 4   | Vibration Fatigue               | Directions: X,Y and Z Duration: 2h                                      |  |  |
| 5   | Drop Test                       | Cycle time: 10 times Height: 1.0m                                       |  |  |
|     |                                 | Temperature: 245 ℃ ±5 ℃ Duration: 3.0s5.0s                              |  |  |
| 6   | Solder Ability Test             | Depth: DIP2/3 , SMD1/5  |  |  |
|     |                                 | (1)Thickness of PCB:1mm , Solder condition: 260 ℃±5 ℃ , Duration: 10±1s |  |  |
| 7   | Resistance to<br>Soldering Heat | (2)Temperature of Soldering Iron: 350℃±10℃, Duration: 3~4s,             |  |  |
|     |                                 | Recovery time: 2 ± 0.5h   |  |  |

# **Recommended Reflow Soldering Diagram**



Reflow cycles:3 cycles max.

197.30MHz SAW Filter SF1643 12.00MHz Bandwidth

#### **Notes**

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.

Please read notes at the end of this document.